

*ABSTRACT AMENDMENT*

Replace the Abstract with:

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The method of producing a multi-layered wiring board includes exposing and developing a photosensitive resin to form holes having ~~a~~ an initial size; depositing and forming a curable resin on the insulating layer, filling the holes, and heating the curable resin to form a cured thin film from only a part of the curable resin ~~on~~ at an interface with the insulating layer ~~and~~, leaving a part of the curable resin uncured; removing the part of the curable resin that is uncured, leaving the cured thin film in place and thereby producing via-holes having ~~an opening~~ openings reduced in size from the initial size of the holes due to the cured thin film remaining in the holes, and filling the via holes with an electrically conducting material.

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